

Through-Hole Solder Joint Evaluation

Training & Reference Guide

IPC-DRM-PTH-G

Now updated
to A-610
Rev. G

DEMO ONLY



Association Connecting Electronics Industries

References:
IPC-A-610 Rev. G
OCT 2017

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Introduction

This Through-Hole Solder Joint Evaluation Training and Reference Guide provides visual examples of acceptability requirements, defects and conditions found in Through-Hole solder joints on electronic assemblies. This manual is intended for use as an illustrated support document to assist in the training and practice of Through-Hole solder joint evaluation, and therefore, it references portions of the following IPC standard:

The IPC-A-610 Rev. G, *Acceptability of Electronic Assemblies*, which illustrates the requirements for many types of solder connections.

Classification

Through-Hole solder joint requirements are divided into three classes depending on the ultimate use, life expectancy and operating environment of the electronic assembly. Those classes are as follows:

Class 1 General Electronic Products

Includes products suitable for applications where the major requirement is the function of the completed assembly, not necessarily for extended life, reliability of service, or cosmetic perfection.

Class 2 Dedicated Service Electronic Products

Includes products where continued performance and extended life is required and for which uninterrupted service is desired but not critical. Typically, the end use environment would not cause failures through extremes of temperature or contamination.

Class 3 High Performance Electronic Products

Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required. These high-reliability type products are used in such systems as life-support and aerospace.

Note: The inspector does not select the class for the part under inspection. Documentation which specifies the applicable class for the part under inspection should be provided to the inspector.

Terminology

Below are the definitions of terms you will run across while using this manual: (taken from IPC-T-50, Terms and Definitions for Interconnecting and Packaging Electronic Circuits)

Clinched Lead - A component lead that is inserted through a hole in a PWB and is then bent or clinched to hold the component in place and to make metal-to-metal contact with a land before soldering.

Cold Solder Connection - A solder connection that exhibits poor wetting, and that is characterized by a gray, porous appearance.

Component - An individual part or combination of parts that, when together, perform a design function.

Conductor - A single conductive (metal) path in a conductive pattern.

Contact angle - The angle formed by the edge of the solder fillet and the land's surface.

Dewetting - A condition that results when molten solder coats a surface and then recedes to leave irregularly-shaped mounds of solder that are separated by area that are covered with a thin film of solder and with the basis metal not exposed.

Disturbed solder connection - A solder connection that is characterized by the appearance that there was motion between the metals being joined when the solder was solidifying.

Excess solder connection - A solder connection that is characterized by the complete obscuring of the surfaces of the connected metals and/or by the presence of solder beyond the connection area.

Fillet - A normally-concave surface of solder that is at the intersection of the metal surfaces of a solder connection.

Flux residue - A flux-related contaminant that is present on or near the surface of a solder connection.

Ice (solder projection) - An undesirable protrusion of solder from a solidified solder joint or coating.

Land - A portion of a conductive pattern that is usually used for making electrical connections, for component attachment, or both.

Lead - The wire or formed metal conductor that extends from a component to serve as a mechanical and/or electrical connector.

continued....

Terminology

Nonwetting - The partial adherence of molten solder to a surface that it has contacted and basis metal remains exposed.

Pinhole - A small hole that penetrates from the surface of a solder connection to a void of indeterminate size within the solder connection.

Plated-through-hole - A hole with plating on its walls (supported hole) that makes an electrical connection between conductive patterns on internal layers, external layers, or both, of a printed board.

Residue - Any visual or measurable form of process-related contamination.

Solder - A metal alloy with a melting temperature that is below 427°C (800°F).

Solderability - The ability of a metal to be wetted by molten solder.

Soldering - The joining of metallic surfaces with solder and without the melting of the base material.

Solder bridging - The unwanted formation of a conductive path of solder between conductors.

Splatter - Extraneous fragments of solder with an irregular shape.

Webbing - A continuous film or curtain of solder that is parallel to, by not necessarily adhering to, a surface that should be free of solder.

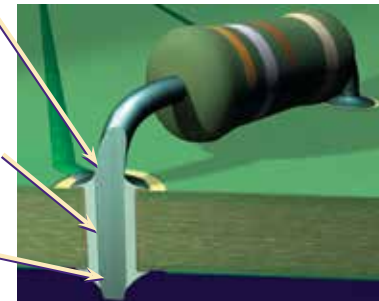
Wetting - The formation of a relatively uniform, smooth, unbroken, and adherent film of solder to a basis metal.

Cross-section View of a Target Plated Through-Hole

Solder
Destination
Side

Barrel

Solder
Source
Side



Solder Destination Side: The side of a through-hole assembly containing the most component bodies. Also called the "primary side" or sometimes the "component side."

Solder Source Side: The side that is coated with solder in the solder wave machine. Also called the "secondary side."

Acceptance Criteria

In this Training and Reference Guide, criteria are given for each class in one or more of the following levels of condition —

Target
Acceptable
Process Indicator
Defect

Photographs or illustrations of each condition are shown in the left column (examples on opposite page). The level of acceptance, class(es) and description of the illustration are all contained in the right column. In the following examples, definitions of each acceptance criterion are printed to the right of sample photographs. For easier viewing, colored bars connect each photograph or illustration to each description, with a different color used for each acceptance level.

Note: Accept and/or reject decisions must be based on applicable documentation such as contract, drawings, specifications such as IPC-A-610 and IPC J-STD-001 or other referenced documents.

Lead Free Soldering

The primary difference between the solder connections created with processes using tin-lead alloys and processes using lead free alloys is related to the visual appearance of the solder.

Acceptable lead free and tin-lead connections may exhibit similar appearances, but lead free alloys are more likely to have:

- Surface roughness (grainy or dull)
- Greater wetting contact angles*

All other solder criteria are the same.

*Wetting cannot always be judged by surface appearance. The wide range of solder alloys in use may exhibit from low or near zero degree contact angles to nearly 90 degree contact angles as typical.



Denotes Lead free image

Condition Levels



Target Class 1, 2, 3

A condition that is close to perfect; however, it is a desirable condition and not always achievable and may not be necessary to ensure reliability of the assembly in its service environment.



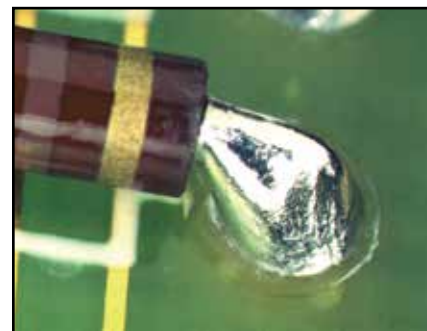
Acceptable Class 1, 2, 3

This characteristic indicates a condition that, while not necessarily perfect, will maintain the integrity and reliability of the assembly in its service environment.



Process Indicator Class 1, 2, 3

A process indicator is a condition that does not affect the form, fit and function of a product. However, process indicators signal a lack of good workmanship to the customer and should be used to improve the manufacturing process—even though the product is considered usable.



Defect Class 1, 2, 3

A defect is a condition that is insufficient to ensure the form, fit or function of the assembly in its end use environment. The manufacturer shall rework, repair, scrap, or "use as is" based on design, service and customer requirements.

Solder Destination Side - Land Coverage



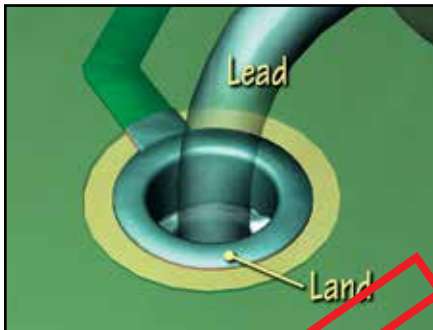
Target Class 1, 2, 3

Properly wetted solder fillet covers 100% of solder destination side land area and feathers out to a thin edge on land area.



Acceptable Class 1, 2, 3

0% of the solder destination side land area is covered with wetted solder.



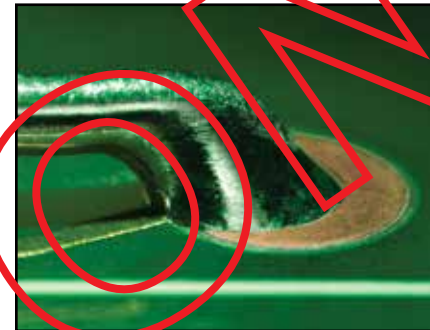
References:
A-610G: 7.3.5.3, Table 7-4

Solder Destination Side - Excess Solder



Target Class 1, 2, 3

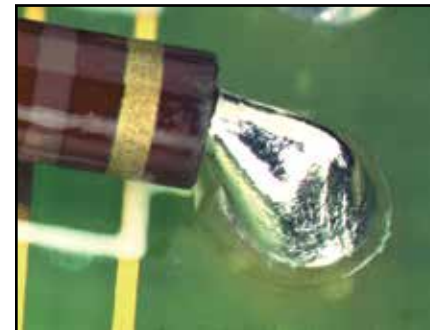
Solder fillet ends below lead bend area.



Acceptable Class 1, 2, 3

Solder in lead bend area does not contact the component body or end seal.

Solder does not obscure the stress relief bend of the component lead.

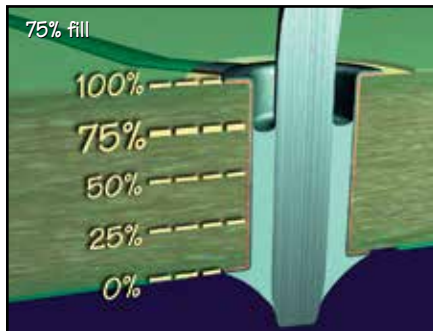


Defect Class 1, 2, 3

Solder in lead bend area comes in contact with the component body or end seal; or obscures the stress relief bend of the component lead.

References:
A-610G: 7.3.5.6, 7.3.5.7

Barrel - Vertical Fill of Solder



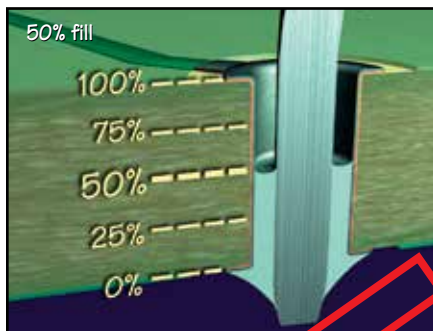
Acceptable Class 2, 3

A minimum of 75% solder fill, or a maximum of 25% depression, including both solder source and solder destination sides, is permitted. Component lead is visible in solder source side of the connection.

Notes:

Minimum acceptable condition for vertical fill of solder on Class 1 assemblies is not specified.

Less than 100% solder fill may not be acceptable in some applications, e.g., thermal shock, electrical performance.



Acceptable Class 2 (14+ Leads)

Defect Class 2 (< 14 Leads)

Defect Class 3

Vertical fill criteria for Class 2 is based on the number of component leads, and if the lead is connected to a thermal plane.

Class 2 components with
Less than 14 leads: 75% fill
Less than 14 leads - connected to thermal plane: 50% fill
14 leads or more: 50% fill

Class 3 requires 75% vertical fill
Maximum 25% depression allowed – on one side or total of both sides.

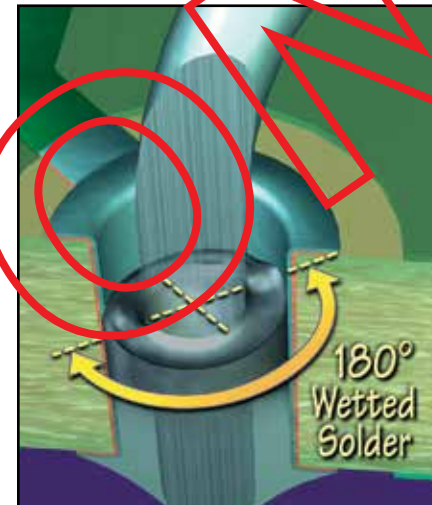
References:
A-610G: 7.3.5.1, Table 7-4

Barrel - Wetting of Lead & Barrel



Target Class 1, 2, 3

100% (360°) circumferential wetting present on solder destination side of **lead** and **barrel**. Vertical fill at 100%.

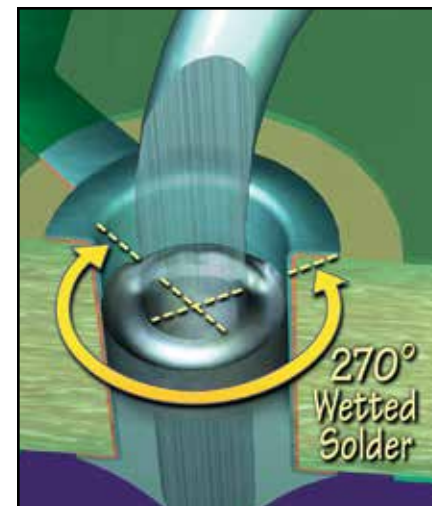


Acceptable Class 2

A minimum of 180° circumferential wetting (50%) present on solder destination side of **lead** and **barrel**.

Note:

Minimum acceptable condition for circumferential wetting of lead and barrel on solder destination side for Class 1 is not specified.



Acceptable Class 3

A minimum of 270° circumferential wetting (75%) present on solder destination side of **lead** and **barrel**.

References:
A-610G: 7.3.5.2, Table 7-4

Solder Source Side - Wetting of Lead, Land & Barrel



Target Class 1, 2, 3

100% solder fillet and circumferential wetting present on solder source side of solder joint.



Acceptable Class 1, 2

A minimum of 270° circumferential (75%) wetting present on solder source side of **lead, land and barrel**.



Acceptable Class 3

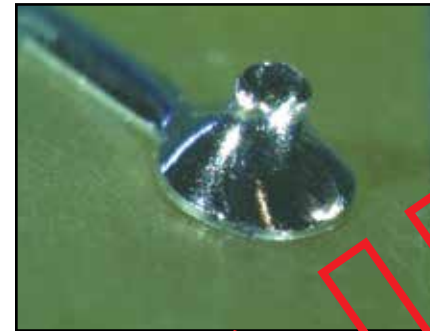
A minimum of 330° circumferential (approx. 90%) wetting present on solder source side of **lead and barrel**.



A minimum of 270° circumferential (75%) wetting for the **land**.

References:
A-610G: 7.3.5.4, 7.3.5.5

Solder Source Side - Contact Angle



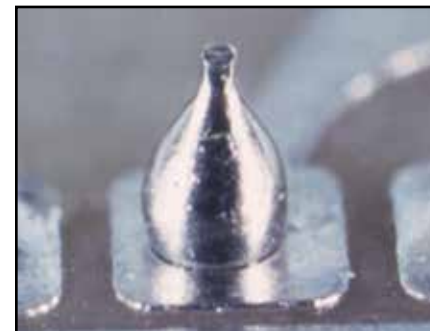
Target Class 1, 2, 3

The solder fillet forms a contact angle of 90° or less.



Acceptable Class 1, 2, 3

The solder fillet forms a contact angle of more than 90° due to quantity of solder extending over the edge of the land.



Defect Class 1, 2, 3

Nonwetting results in the solder forming a ball or beading on the surface. The fillet is convex and the contact angle is greater than 90°, but solder does not extend over the land. (See notes on page 5, lead free wetting contact angles.)



Very poor wetting results in the solder clumping on the surface. No feathered edge is apparent. Contact angle is irregular.

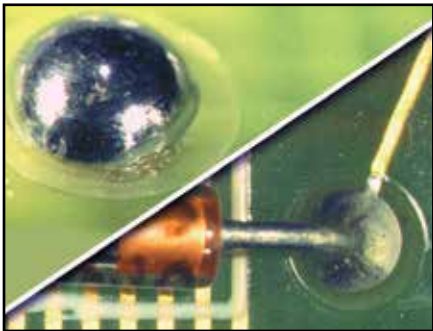
References:
A-610G: 5, 5.1

Solder Source Side - Discerning the Lead



Target Class 1, 2, 3

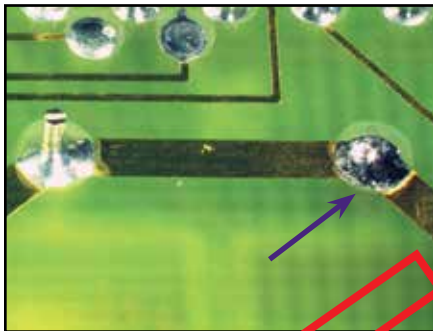
Lead and land are well wetted, solder source side lead is clearly visible. Solder fillet is concave.



Acceptable Class 1

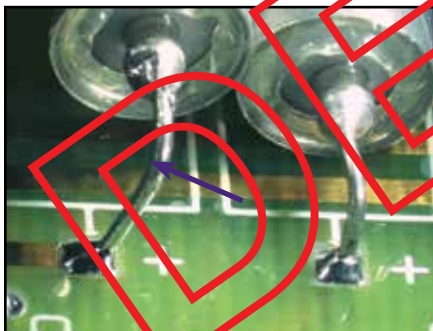
Process Indicator Class 2, 3

Fillet is slightly convex with good wetting, and the lead is not discernible on the solder source side due to excess solder. However, visual evidence of the lead in the hole can be determined on the solder destination or primary side.



Defect Class 1, 2, 3

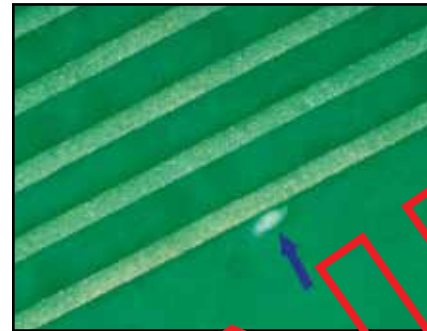
Lead not discernible on solder source side due to lifted component or bent lead on solder destination or primary side. Solder not wetted to lead or land.



Lifted component or bent lead on solder destination side, causing an undiscernable lead on the solder source side.

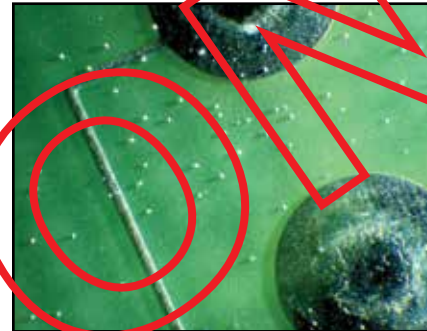
References:
A-610G: 7.3.5

Solder Balls



Acceptable Class 1, 2, 3

Encapsulated solder ball that does not violate minimum electrical clearance.



Defect Class 1, 2, 3

Solder balls not entrapped in no-clean residue or encapsulated with conformal coating/solder mask, or not attached (soldered) to a metal surface, or that violate minimum electrical clearance.

Notes:

Entrapped/encapsulated/attached is intended to mean the service environment of product will not cause a solder ball to become dislodged.

References:
A-610G: 5.2.7.1

Solder Bridging



Defect

Class 1, 2, 3

Solder bridging across (noncommon) adjacent lands.



Solder has bridged to (noncommon) adjacent lands.

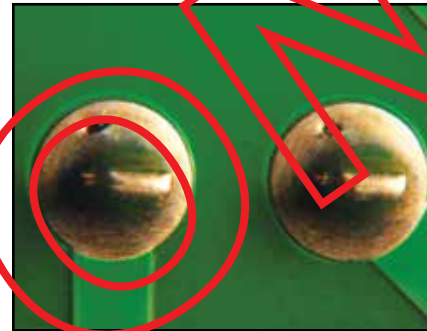
Cavities, Voids, Pinholes, Blowholes, etc



Target

Class 1, 2, 3

No void areas or surface imperfections. Lead and circuitry are well wetted.



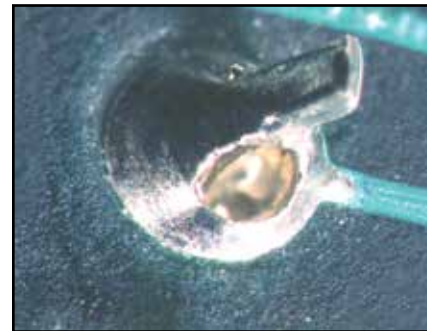
Acceptable

Class 1

Process Indicator

Class 2, 3

Solder cavities which do not reduce circumferential wetting of lead and barrel, land coverage, or vertical fill below minimum acceptable requirements for class.



Defect

Class 1, 2, 3

Solder cavities that reduce circumferential wetting of lead and barrel, land coverage or vertical fill below minimum acceptable requirements for class.

References:
A-610G: 5.2.7.2

References:
A-610G: 5.2.2

Cold Solder Joint



Target

Class 1, 2, 3

Solder joint is smooth, shiny to satin luster, well wetted on entire land and lead.



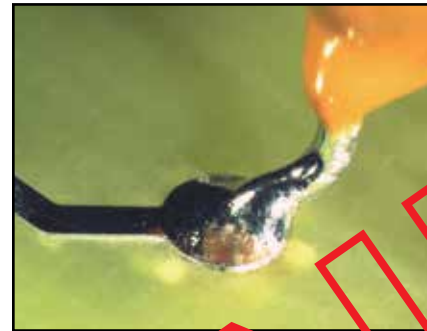
Defect

Class 1, 2, 3

Cold solder joint: lumpy and poorly wetted to land and lead.

References:
A-610G: 5.2.5

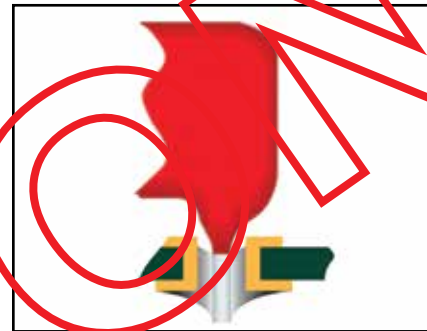
Coating Meniscus in Solder Joint



Target

Class 1, 2, 3

For coated or sealed components, there is a 1.2 mm or greater separation between the component coating meniscus and the solder fillet.



Acceptable

Class 1, 2

Components with a coating meniscus can be mounted with the meniscus into the solder provided there is 360° wetting (lead to land) on the solder source side. The lead coating meniscus is not discernible on the solder source side.



Process Indicator

Class 2, 3

Coating meniscus extends into the plated through-hole but - but is not embedded in the solder joint.



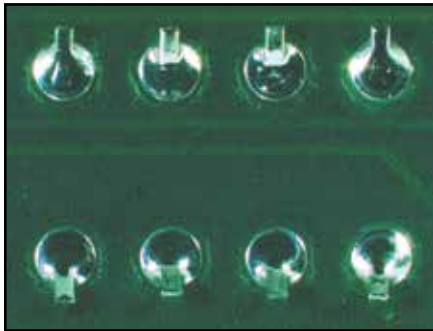
Defect

Class 3

Coating meniscus is embedded in the solder connection.

References:
A-610G: 7.3.5.8, Table 7-4

Corrosion / Surface Appearance

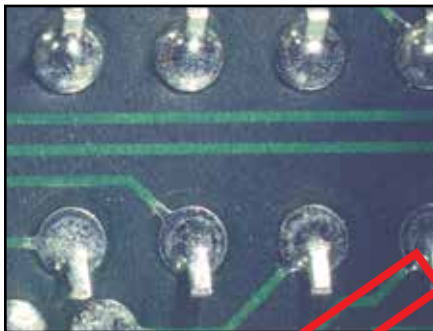


Target Class 1, 2, 3

Shiny to satin luster and clean metallic surfaces.



Surface of lead free solder joints may be grainy or dull.



Acceptable Class 1, 2, 3

Slight dulling of clean metallic surfaces.



Defect Class 1, 2, 3

Colored residues or rusty appearance on metallic surfaces or hardware, or other evidence of corrosion.

References:
A-610G: 10.6.5

Disturbed Solder Joint



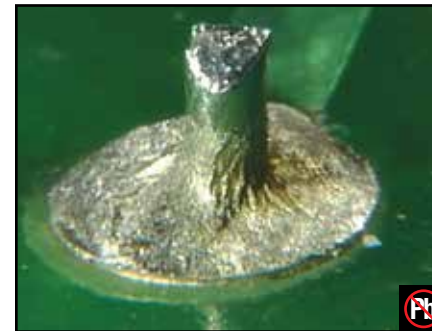
Target Class 1, 2, 3

Solder joint is smooth shiny to satin luster, well wetted on entire land and lead.



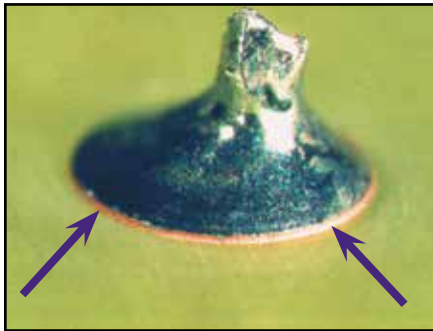
Defect Class 1, 2, 3

Disturbed solder joint: has uneven surface from movement in the connection while cooling.



References:
A-610G: 5.2.8

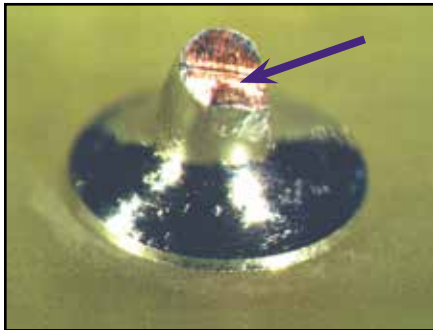
Exposed Basis Metal



Acceptable

Class 1, 2, 3

Exposed copper on vertical conductor edges.



Exposed basis metal at cut ends of component leads or wires.

Notes:

Exposed basis metal on component leads, conductors or lands from nicks, scratches, dents, etc., are :

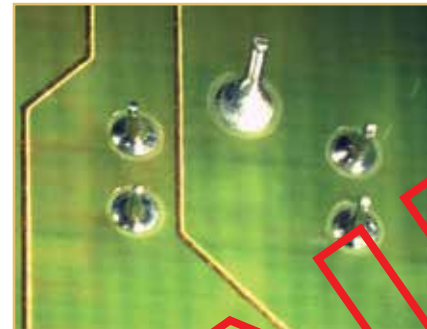
Acceptable - Class 1,

Process Indicator - Class 2, 3

Provided solder connection meets requirements for lead, conductor and lands.

Certain board and conductor finishes may exhibit solder wetting only to specific areas. Exposed basis metal is acceptable in these circumstances, if all other requirements are met.

Foreign Object Debris (FOD)



Acceptable

Class 1, 2, 3

FOD - Foreign Object Debris is attached / entrapped, or encapsulated on assembly surface or solder mask, and does not violate minimum electrical clearance.



Defect

Class 1, 2, 3

Dirt, lint, dross, wire clippings, or other particulate matter on assembly that are not attached, entrapped or encapsulated — or that violate minimum electrical clearance.

Lead Cutting / Fractured Solder Joint



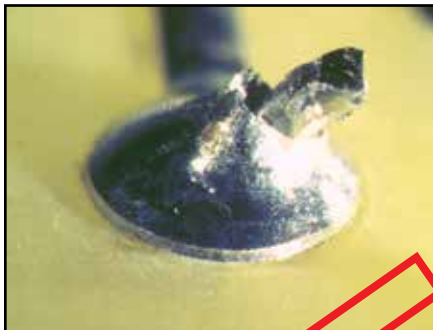
Acceptable Class 1, 2, 3

No fractures between lead and solder.



Defect Class 1, 2, 3

Fractured solder connection.

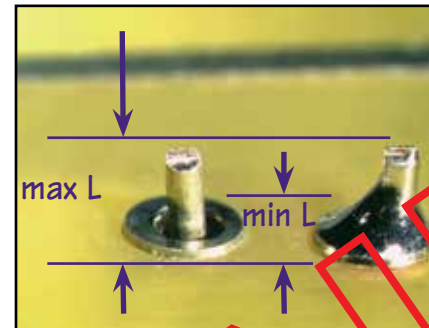


Notes:
Applies to printed board assemblies where the solder source side has had leads trimmed after soldering. For classes 2 and 3, the solder joints need to be either reflowed or visually inspected at 10X to ensure that the solder connection has not been damaged or deformed. Lead trimming that cuts into solder fillets shall be reflowed.



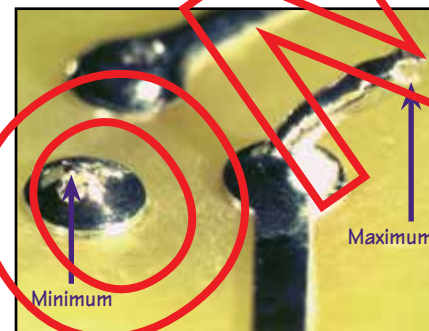
References:
A-610G: 7.3.5.9

Lead Protrusion



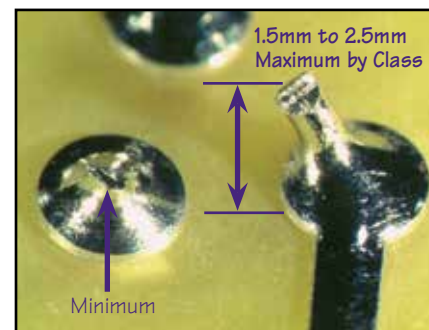
Target Class 1, 2, 3

The protrusion of leads beyond the conductive surface is within the specified minimum and maximum of dimension "L."



Acceptable Class 1

The lead end is visible in the solder joint (minimum) and there is no danger of violating electrical spacing or causing shorts (maximum).



Acceptable Class 2, 3

The lead end is visible in the solder joint (minimum) and extends no more than 2.5 mm (Class 2), or extends no more than 1.5 mm (Class 3) from the top of the land (maximum) provided there is no danger of violating electrical clearance, or exceeding maximum design height requirements.

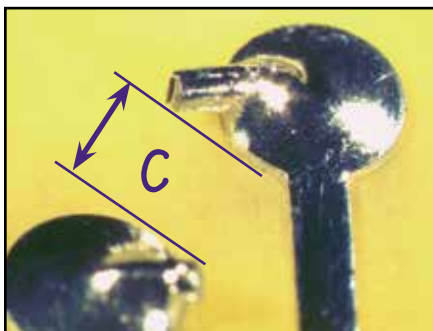
References:
A-610G: 7.3.3, Table 7-3, Figs. 7-72 7-74

Lead Protrusion / Clinched



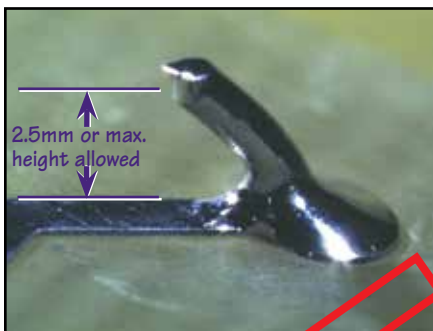
Target Class 1, 2, 3

Lead end is parallel to the board and direction of the clinch is along the connecting conductor.



Acceptable Class 1, 2, 3

The clinched lead does not violate the minimum electrical clearance (C) between non-common conductors, and is not greater than the similar length allowed for straight-through leads.



Defect Class 1, 2, 3

The clinched lead extends more than the maximum height allowed for straight-through leads for its class. (Partially clinched leads for part retention shall be considered as unclynched leads, and need to meet protrusion requirements.)



References:
A-610G: 7.3.4

Nonwetting of Solder



Target Class 1, 2, 3

The solder fillet appears generally smooth and exhibits good wetting of the solder to the parts being joined. The outline of the parts is easily determined. A feathered edge is created by the solder at the part being joined.



Acceptable Class 1, 2, 3

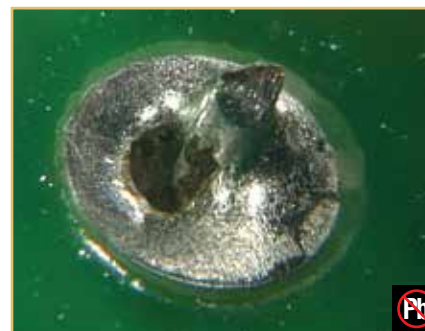
The solder connection must indicate evidence of wetting and a smooth blend of solder to the surface forming a contact angle of 90° or less.

(Also see page 12, Solder Source Side - Contact Angle)



Defect Class 1, 2, 3

Non-wetting results in the solder forming a ball or beading on the surface. The fillet is convex; no feathered edge is apparent.



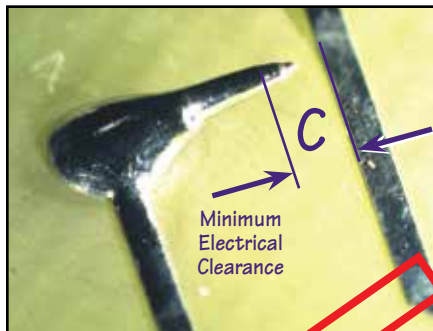
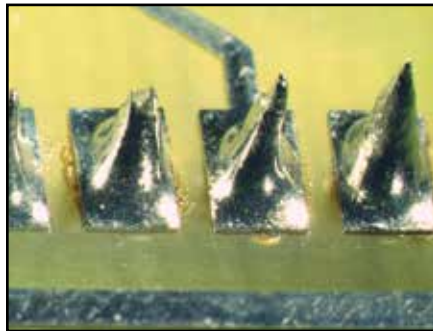
References:
A-610G: 5.2.4

Projections



Defect Class 1, 2, 3

Solder projections that violate spacing or height requirements of the assembly design (assembly could short out to adjacent board or frame when placed in final system position).



Solder projections that violate Minimum Electrical Clearance (C).

References:
A-610G: 5.2.10

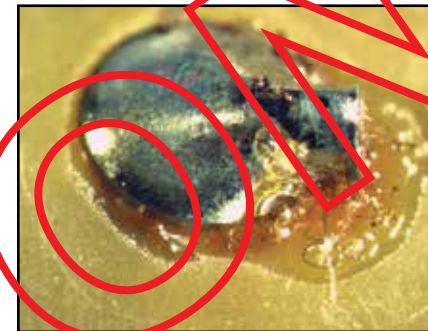
Residue



Target Class 1, 2, 3

No visible flux residue.

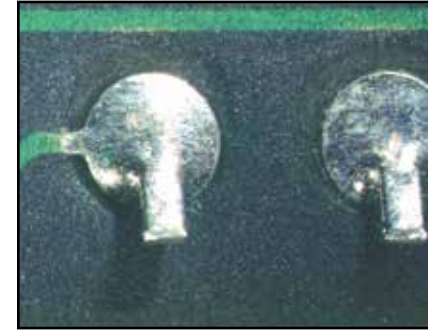
Note: Flux residues from "no-clean" processes may be allowed.



Defect Class 1, 2, 3

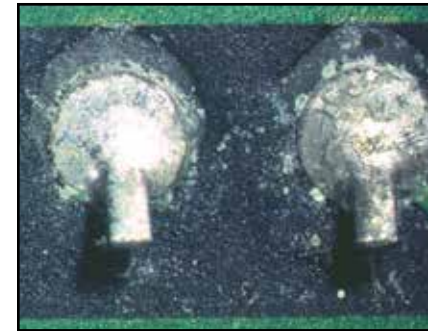
Visible residue from "cleanable" fluxes, or any active flux residues on electrical contact surfaces.

Notes: Class 1 may be acceptable after qualification testing. Check also for flux entrapment in and under components. Processes designated "no clean" need to comply with end product cleanliness requirements.



Target Class 1, 2, 3

All assembly surfaces are clean, no visible residues.



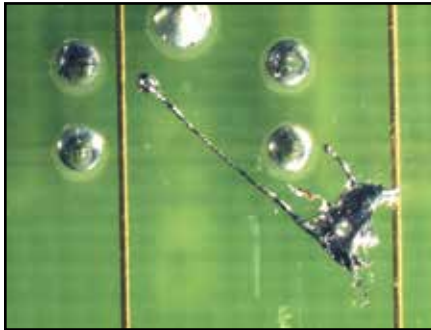
Defect Class 1, 2, 3

Metallic areas exhibit crystalline white deposits. White residue on PCB surface, on or around soldered termination.

Note: White residues resulting from no-clean or other processes are acceptable provided the residues from chemistries used have been qualified as harmless.

References:
A-610G: 10.6.1, 10.6.3

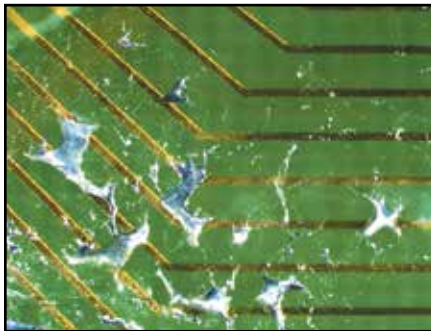
Splashes of Solder / Webbing



Defect

Class 1, 2, 3

Solder splashes that are not attached, entrapped or encapsulated — or that violate minimum electrical clearance. Solder splashes on metal component surfaces that impact form, fit or function.



Solder webbing.

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References:
A-610G, 5.2.7.3

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